Line	Part number	Description	Qty
10	8122 460 10121	LASER1205 UV Dicing	3
20	8122 460 10241	Exhaust Keller Dust Collector VARIO T1.0 incl Safety valve 3-4 laser tools	1
30	8122 467 98751	Keller Exhaust option: Additional Charge for Safety filter for GaAs	1
40	4722 070 39091	PROCESS ENGINEER 5 DAYS ON-SITE	6
50	4722 070 38901	SW SECS/GEM TOOL	3
60	4722 070 38881	SW BROKEN WAFER	3

The Basic LASER 1205 UV Dicing System consists of:

- 1 x UV Q301-1000T laser unit (12 months warranty)
- 2 x independent cassette (un)loading stations
- 1 x priority/inspection wafer(un)loading port
- 1 x RDU – Rotary DOE Unit
- 1 x ASF – Automatic Spatial Filter
- 1 x DOE type 6UV20
- 1 x unique dicing stage for 150mm wafers
- 1 x dicing chuck
- 1 x wafer frame handling system for Frame 8" type
- 1 x pre-alignment station
- 1 x Quick exchange arm
- 1 x barcode scanner for cassette level
- 1 x barcode scanner for wafer tape frame level
- 1 x Alignment & Removal Tool set